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(12) **United States Design Patent**
Parekh

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(54) **SOLDER PAD**

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(73) Assignee: **LUMILEDS HOLDING B.V.**,
Schiphol (NL)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/550,889**

(22) Filed: **Jan. 7, 2016**

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/120, 121, 133, 162, 179, 180, 182;
D14/130, 486; D26/1; D15/144.2
CPC H05K 1/111-1/114
See application file for complete search history.

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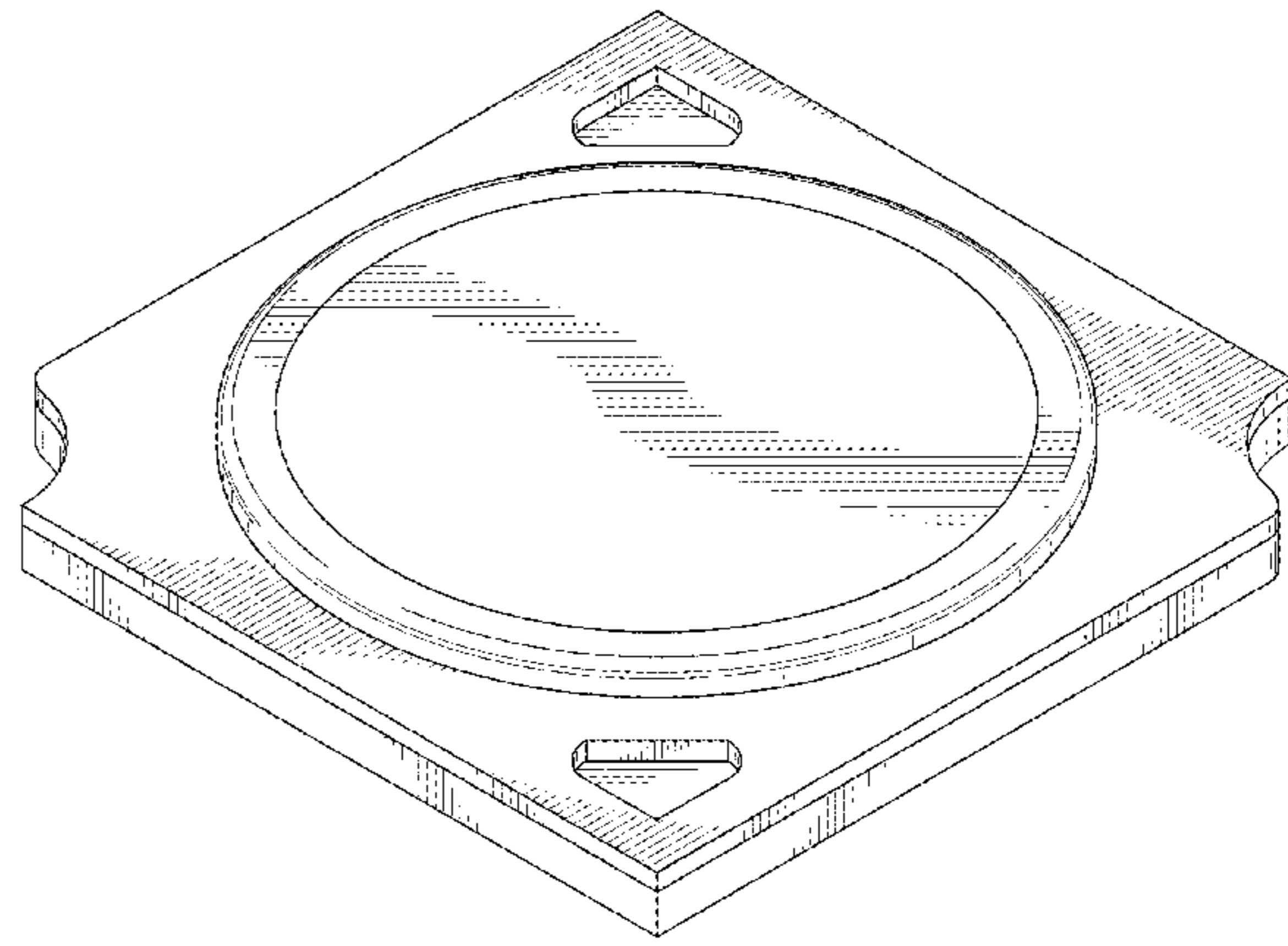
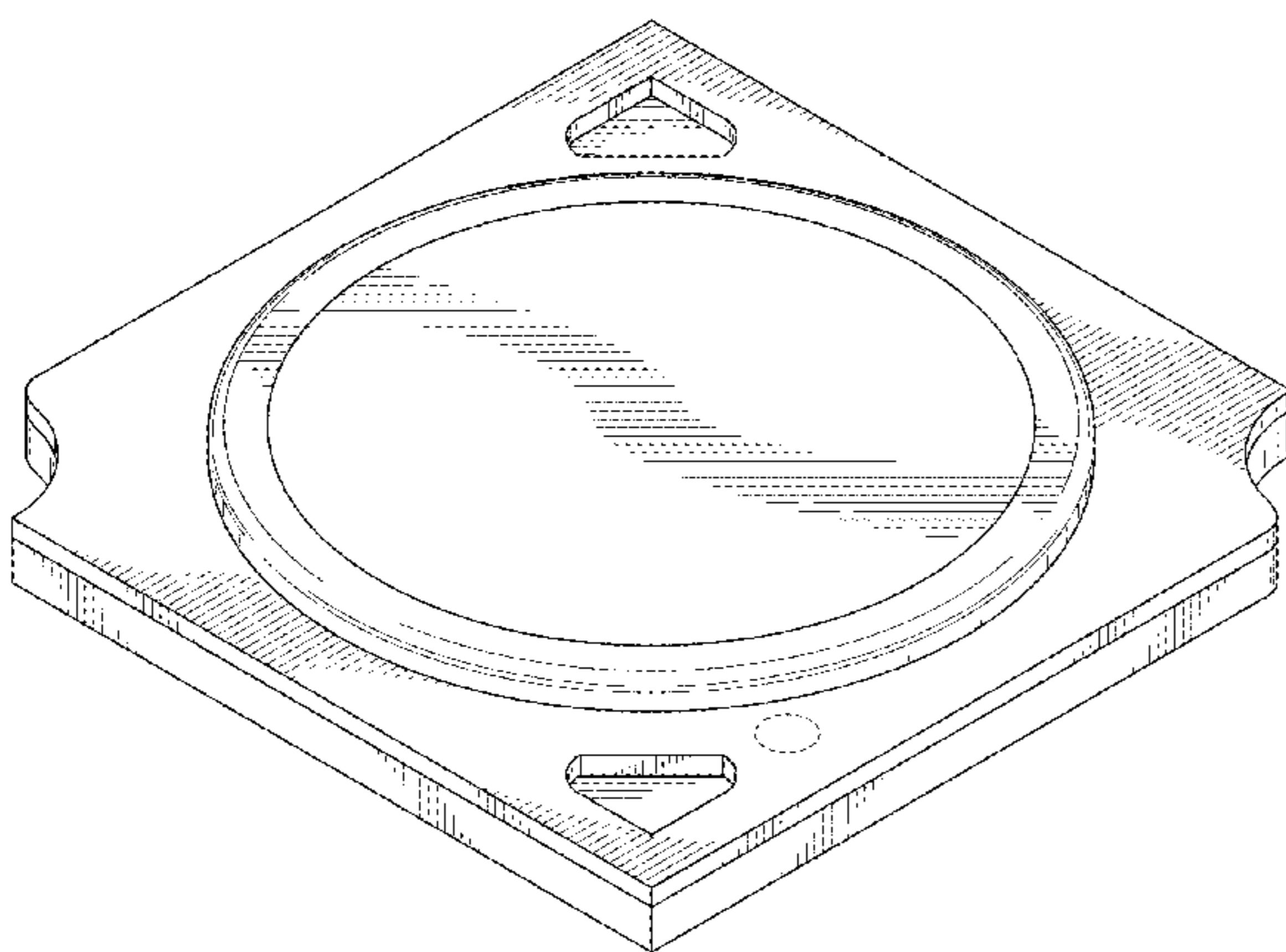
(57) **CLAIM**

The ornamental design for a solder pad, as shown and described.

DESCRIPTION

FIG. 1 is a front, left, and top perspective view of a first embodiment of a solder pad in accordance with my design; FIG. 2 is a top plan view thereof; FIG. 3 is a front elevation view thereof; FIG. 4 is a rear elevation view thereof; FIG. 5 is a left elevation view thereof; and FIG. 6 is a right elevation view thereof; FIG. 7 is a front, left, and top perspective view of a second embodiment of a solder pad in accordance with my design. FIG. 8 is a top plan view thereof; FIG. 9 is a front elevation view thereof; FIG. 10 is a rear elevation view thereof; FIG. 11 is a left elevation view thereof; and FIG. 12 is a right elevation view thereof. All broken lines shown in the drawings depict portions of the solder pad that form no part of the claimed design.

1 Claim, 6 Drawing Sheets



(56)

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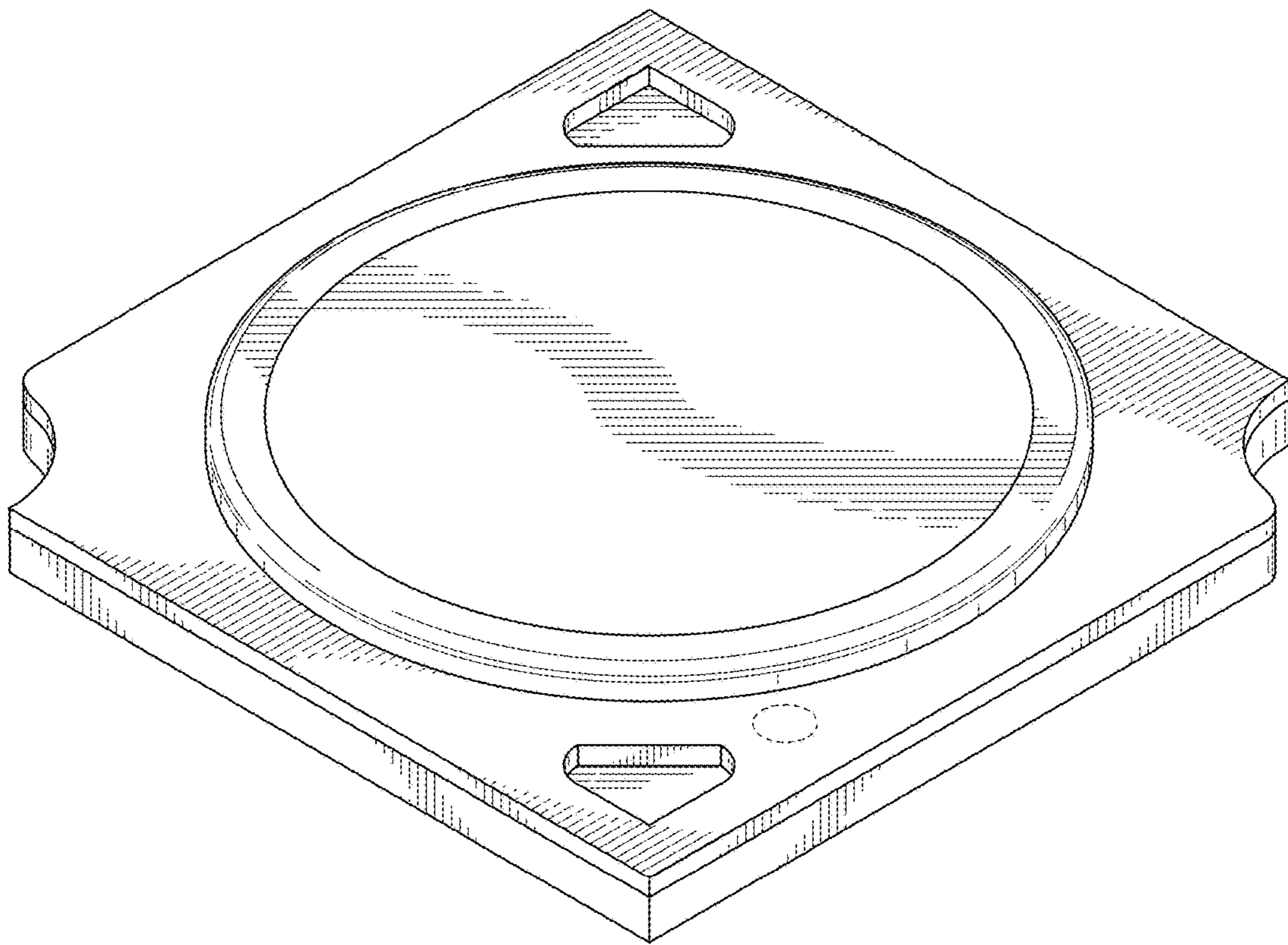


FIG. 1

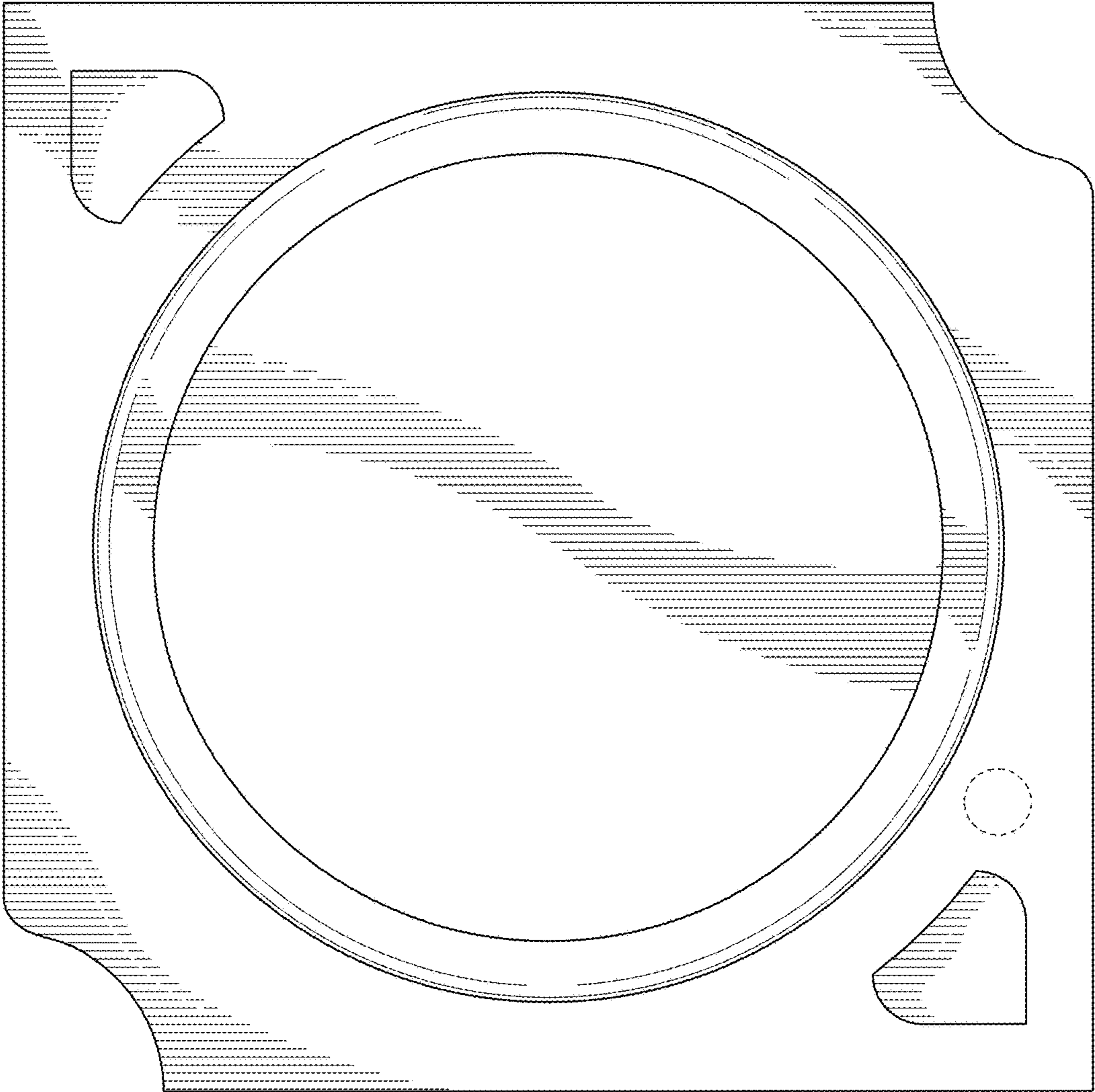


FIG. 2

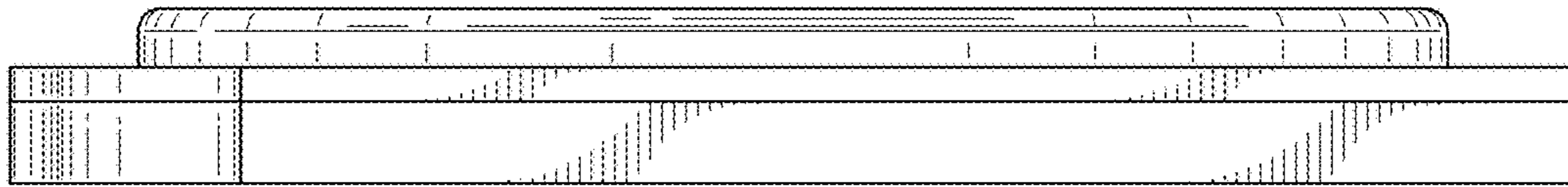


FIG. 3

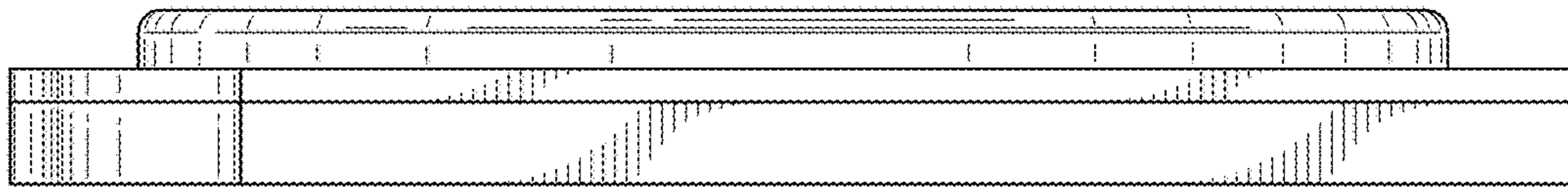


FIG. 4

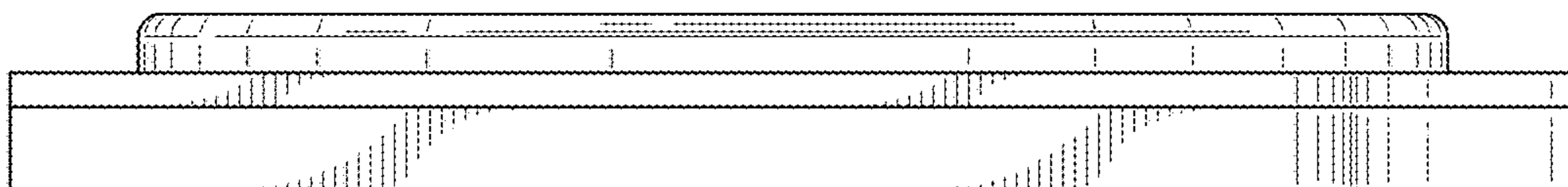


FIG. 5

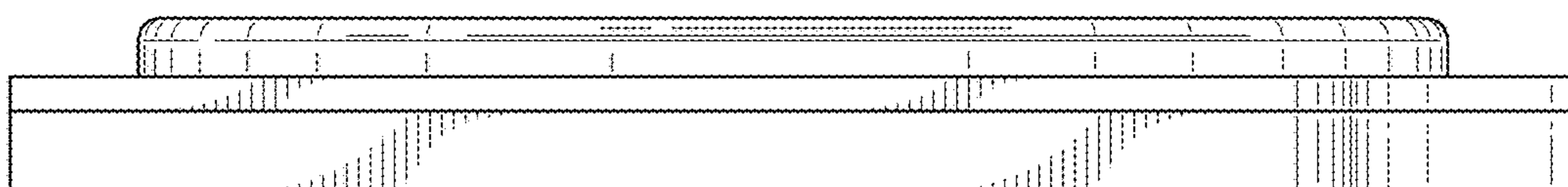


FIG. 6

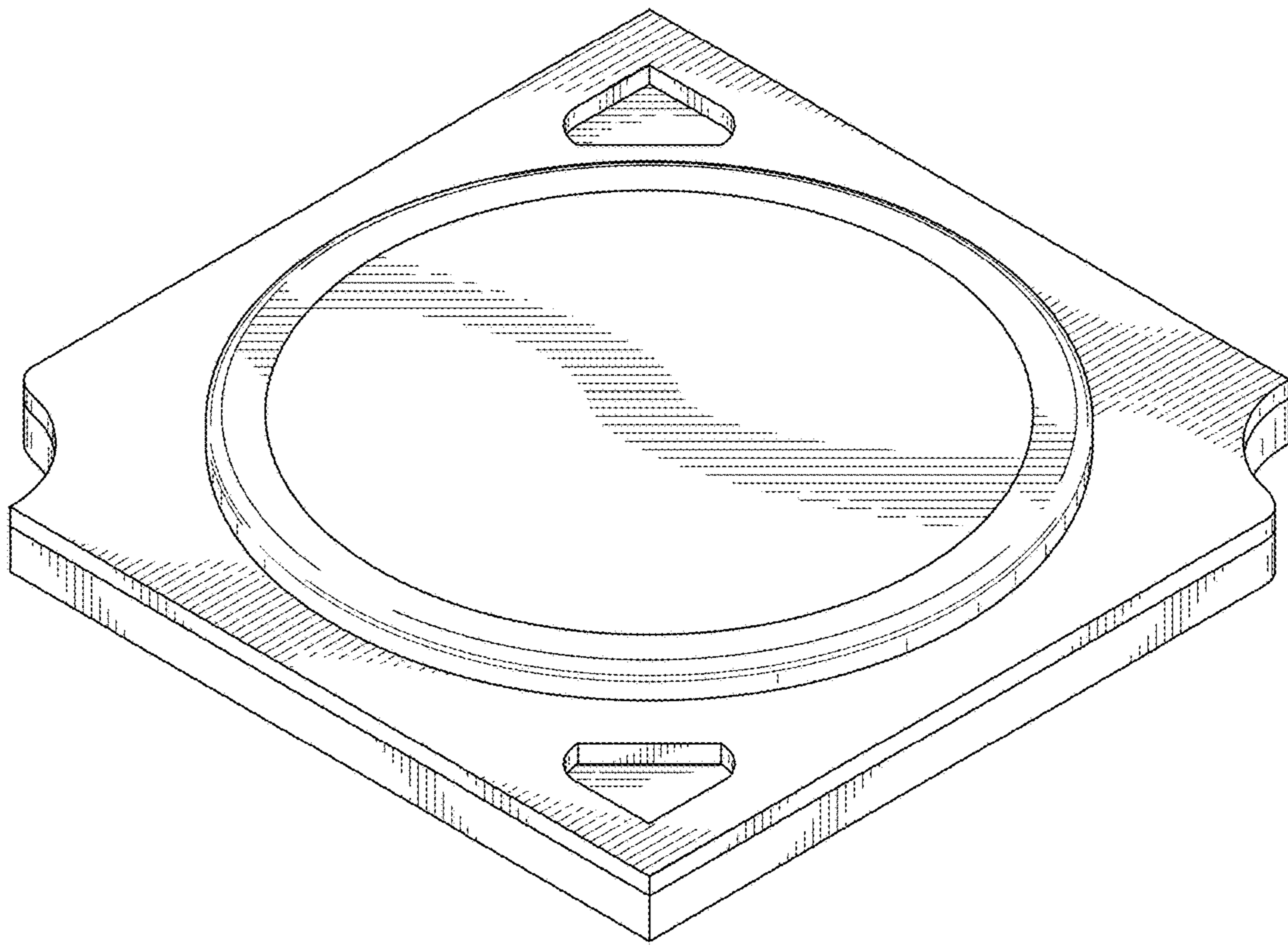


FIG. 7

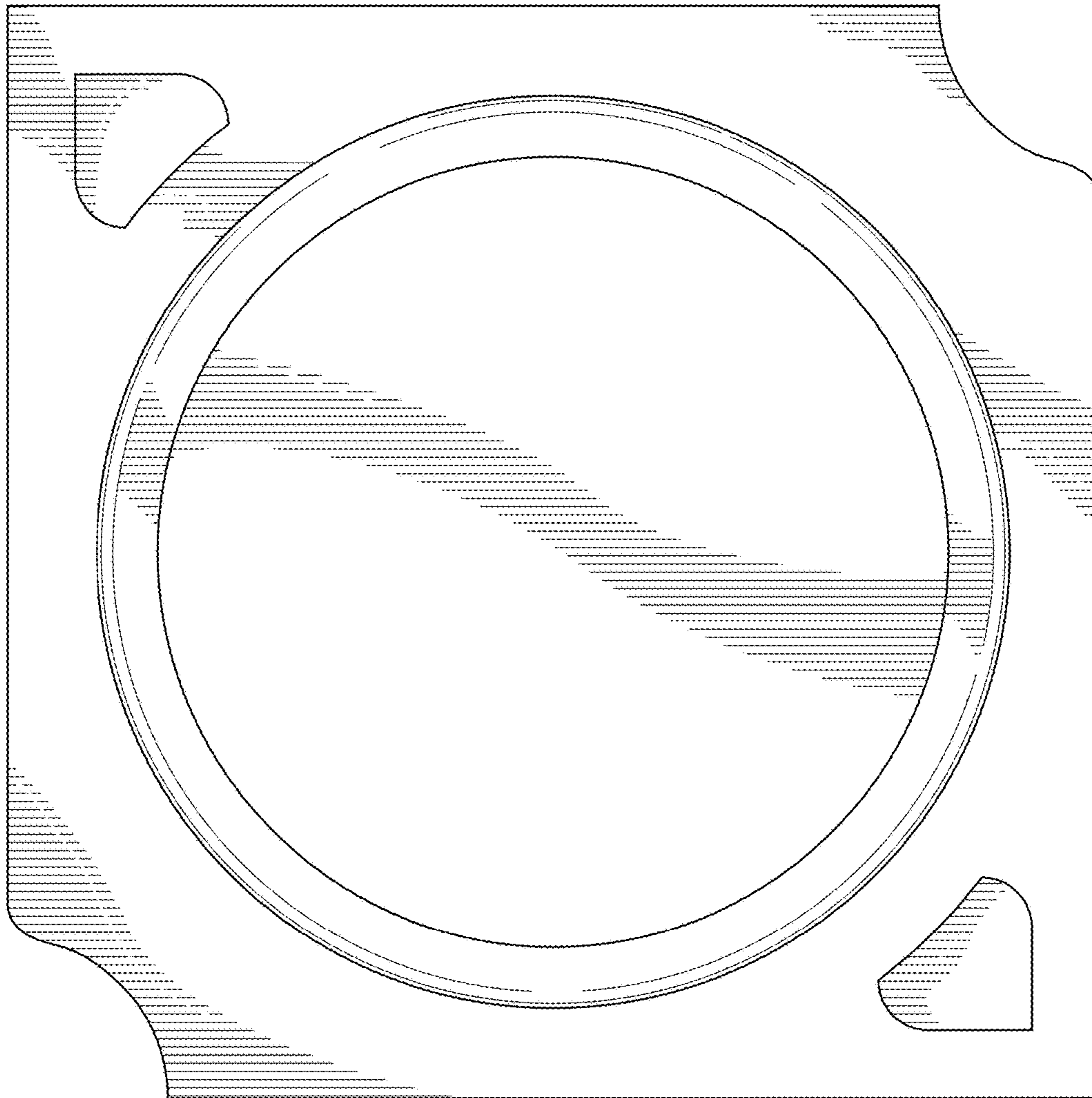


FIG. 8

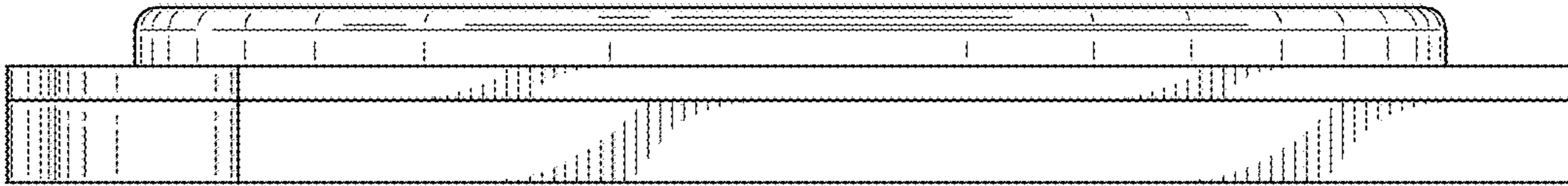


FIG. 9

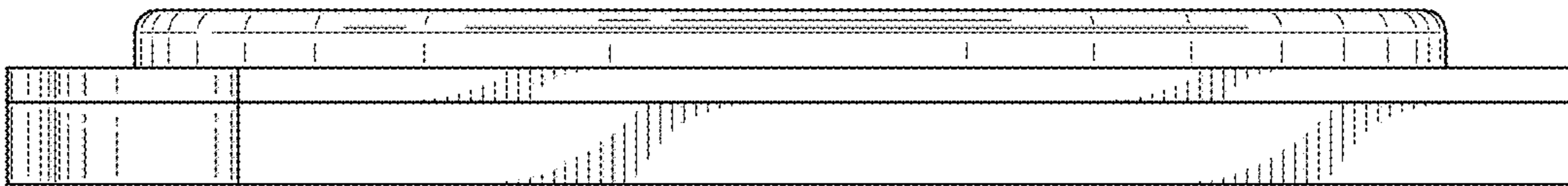


FIG. 10

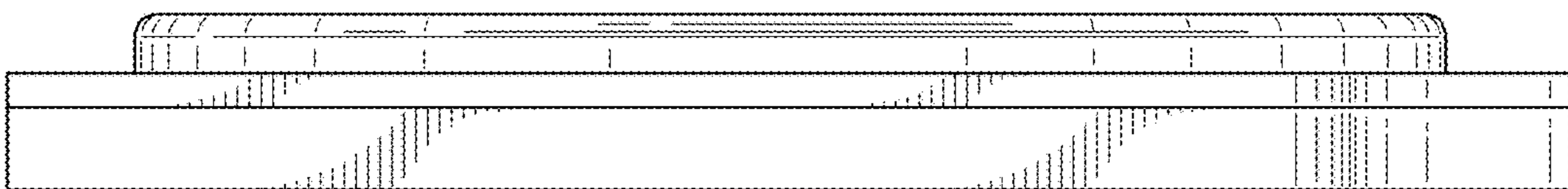


FIG. 11

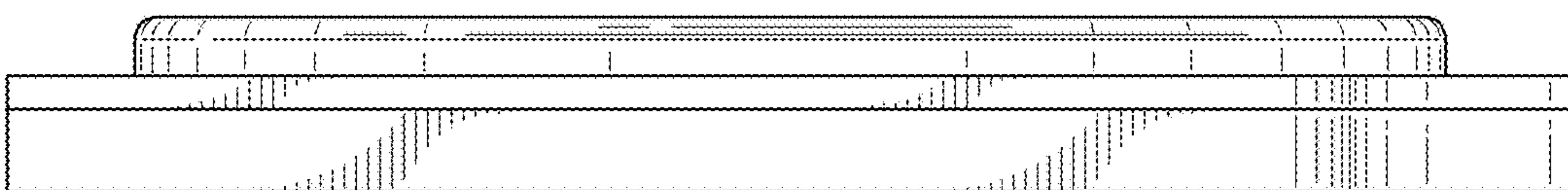


FIG. 12